4 Channel EMI Pi-Filter Array with ESD Protection +4 ESD Diodes

This device is a 4 channel EMI filter array for data lines. Greater than -40~dB attenuation is obtained at frequencies from 800~MHz to 2.2~GHz. It also offers ESD protection – clamping transients from static discharges to protect delicate data line circuitry. It is offered in $300~\mu m$ and $350~\mu m$ solder spheres.

Features

- EMI Filtering and ESD Protection for Data Lines
- Integration of 26 Discretes Offers Cost and Space Savings
- Exceeds IEC61000-4-2 (Level 4) Specifications
- Low Profile Flip-Chip Packaging
- MSL 1
- 300 µm Solder Spheres (NUF4105), Case 499D

Typical Applications

- EMI Filtering and ESD Protection for Data Lines
- Cell Phones
- Handheld Portables
- Notebook Computers
- MP3 Players

MAXIMUM RATINGS $(T_A = 25^{\circ}C)$

Rating	Symbol	Value	Unit
ESD Discharge IEC61000–4–2, – Air Discharge – Contact Discharge Human Body Model	V _{PP}	30 30 16	kV
DC Power per Resistor	P_{R}	100	mW
DC Power per Package	P _T	400	mW
Junction Temperature	TJ	150	°C
Operating Temperature Range	T _{op}	-40 to +85	°C
Storage Temperature Range	T _{stg}	-55 to +150	°C

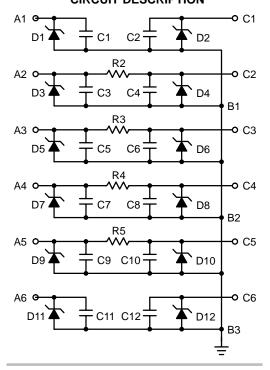
Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.



ON Semiconductor®

http://onsemi.com

CIRCUIT DESCRIPTION





FLIP-CHIP CASE 499D 300 µm Bumps

DEVICE MARKING

NUF4105YYWW

YY = Year WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping [†]
NUF4105FCT1	Flip-Chip	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Symbol	Characteristic	Min	Тур	Max	Unit
V_{BR}	$I_Z = 10 \text{ mA}$	6.0	7.0	8.0	V
I _R	V _{RM} = 3.3 V per line	-	-	0.1	μΑ
R _{I/O}	$I_R = 20 \text{ mA}$	80	100	120	Ω
C _{line}	$V_{R=} 2.5 \text{ V}, f = 1.0 \text{ MHz (Note 1)}$	-	53	-	pF

^{1.} Measured from input/output pins to ground.

TYPICAL PERFORMANCE CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise specified})$

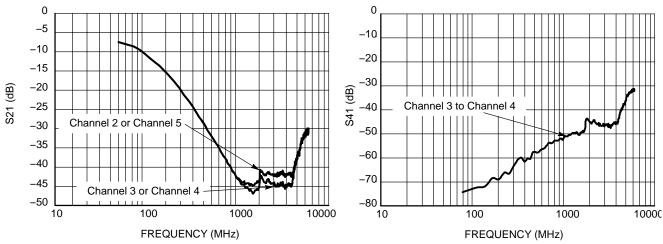


Figure 1. Insertion Loss Curve

Figure 2. Analog Crosstalk Curve

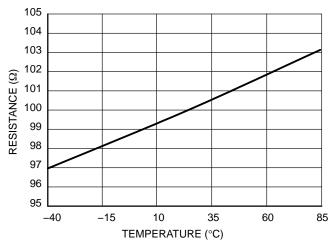


Figure 3. Resistance Over Temperature

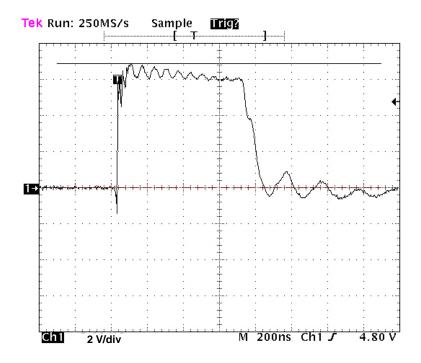


Figure 4. ESD Response for Human Body Model (+8.0 kV)

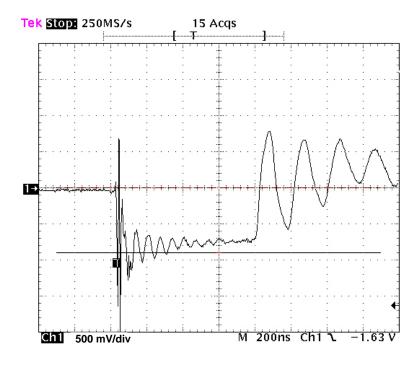


Figure 5. ESD Response for Human Body Model (-8.0 kV)

Printed Circuit Board Recommendations

Parameter	500 μm Pitch 300 or 350 μm Solder Ball
PCB Pad Size	250 μm +25 -0
Pad Shape	Round
Pad Type	NSMD
Solder Mask Opening	350 μm ±25
Solder Stencil Thickness	125 μm
Stencil Aperture	250 x 250 μm sq.
Solder Flux Ratio	50/50
Solder Paste Type	No Clean Type 3 or Finer
Trace Finish	OSP Cu
Trace Width	150 μm Max

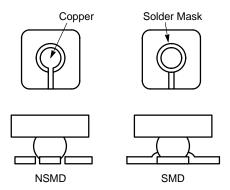


Figure 6. Solder Mask versus Non-Solder Mask Definition

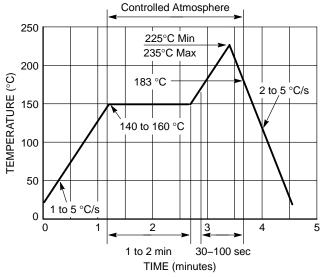
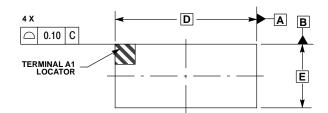


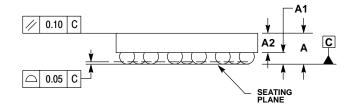
Figure 7. Solder Reflow Profile

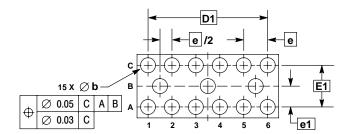
PACKAGE DIMENSIONS

15 PIN FLIP-CHIP CSP

CASE 499D-01 ISSUE O







- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

	MILLIMETERS		
DIM	MIN	MAX	
Α		0.700	
A1	0.210	0.270	
A2	0.380	0.430	
D	2.960 BSC		
Е	1.330 BSC		
b	0.290	0.340	
е	0.500 BSC		
e1	0.435 BSC		
D1	2.500 BSC		
E1	0.870 BSC		

ON Semiconductor and are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability, arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 61312, Phoenix, Arizona 85082–1312 USA Phone: 480–829–7710 or 800–344–3860 Toll Free USA/Canada Fax: 480–829–7709 or 800–344–3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800–282–9855 Toll Free USA/Canada

Japan: ON Semiconductor, Japan Customer Focus Center 2–9–1 Kamimeguro, Meguro–ku, Tokyo, Japan 153–0051 Phone: 81–3–5773–3850

ON Semiconductor Website: http://onsemi.com

Order Literature: http://www.onsemi.com/litorder

For additional information, please contact your local Sales Representative.